

ABSTRACT

5 A ceramic package and a chip resistor obtained by
forming, on a plastic ceramic green sheet comprising 100
parts by weight of a ceramic powder mainly composed of
borosilicate glass, into which 10 to 30 parts by weight
of an acrylic copolymer obtained by polymerizing 100
parts by weight of a (meth)acrylic acid ester and 1 to 10
parts by weight of a monomer having a functional group of
10 a hydroxyl group, acid amide group, or amino group and
having a Tg in the range of -30°C to $+10^{\circ}\text{C}$ is compounded,
a conductor layer using a plastic conductive paste
obtained by compounding, into 100 parts by weight of a
conductive powder, 5 to 20 parts a mixture of an acrylic
15 copolymer having a Tg of not more than -30°C and an
ethylcellulose-based binder, press forming the resultant
single layer of ceramic green sheet, and calcining the
resultant ceramic green sheet having the integrally
formed bottom, opening and opening circumferential edge
20 and a method for producing the same.